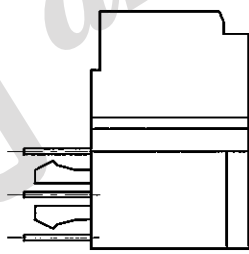
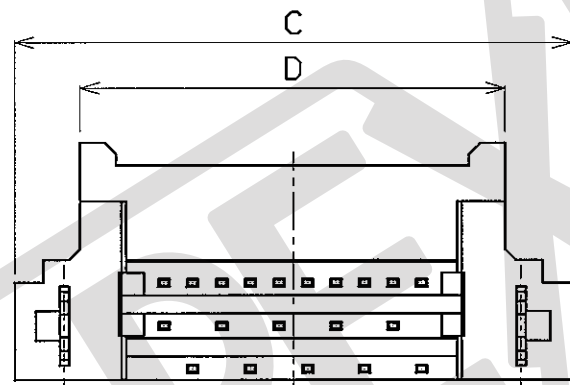
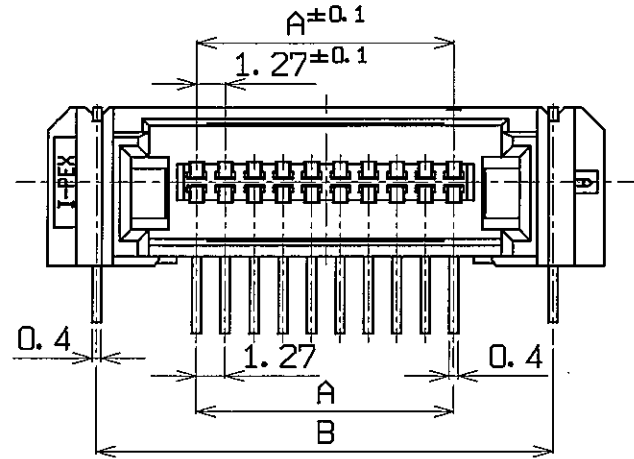
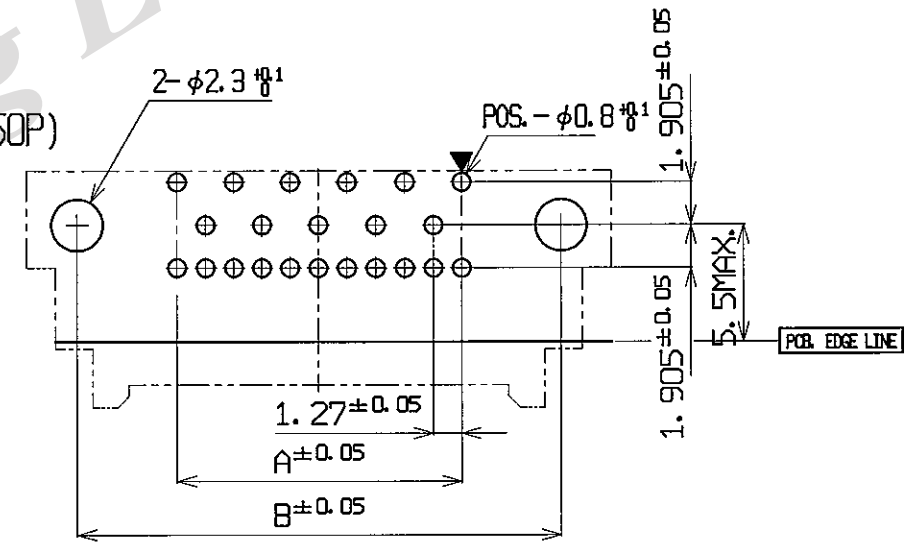
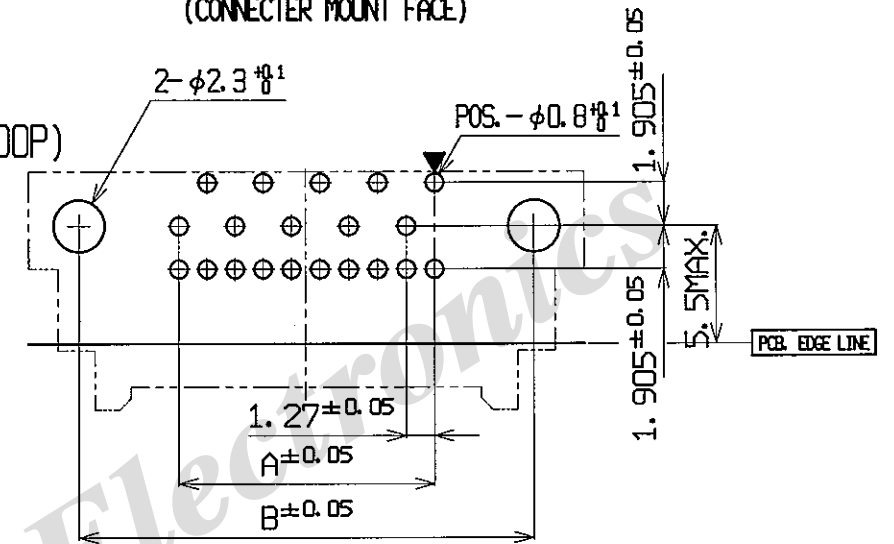


PART NO.	NO. OF POS.	A	B	C	D
20122-020-***	20P	11.43	20.32	24.80	18.90
" -030- "	30P	17.78	26.67	31.15	25.25
" -040- "	40P	24.13	33.02	37.50	31.60
" -050- "	50P	30.48	39.37	43.85	37.95
" -060- "	60P	36.83	45.72	50.20	44.30
" -080- "	80P	49.53	58.42	62.90	57.00
" -100- "	100P	62.23	71.12	75.60	69.70

P/N20122-\*\*\*-\*\*\*  
極数

メッキ仕様(TAIL&HOLD DOWN)  
NOTING : TAIL Sn/Pb , HOLD DOWN Sn/Pb  
F : TAIL Au , HOLD DOWN Sn  
メッキ仕様(Au THK.)  
01:0.05μm MIN.  
02:0.25μm MIN.  
(at 20, 40, 60, 80, 100P)

FOOT PRINT PATTERN  
(CONNECTER MOUNT FACE)



1. MATERIALS:  
NOTES: HOUSING : PPS GF=40%  
94V-0. COLOR: BLACK  
LOCATER PLATE : 66Ny GF=15%  
94V-0. COLOR: BLACK  
CONTACTS&RETAINER : COPPER ALLOY
2. CONTACT FINISH  
Au OVER Ni(1.27μmMIN.) ON CONTACT AREA  
Sn/Pb(1μmMIN.) or Au(0.03μmMIN.)  
OVER Ni(1.27μmMIN.) ON SOLDER TAIL

DESIGN'D BY T. MATSUMOTO				DATE 07/22/96		<b>I-PEX</b> Interconnect and Packaging Electronics TOKYO, JAPAN	TITLE DIFFLINE RECP. R/A(3-ROW)
CHK'D BY T. HARADA				DATE 12/11/96			
APP'D BY Y. FUKUDA				DATE 12/11/96		TOL. ±0.3 , ±2'	DWG. No. 20122
REV. RECORD				CUSTOMER COPY	PROJECTION	SCALE 3/1	UNIT MM
SERIES No.: 2110							SHEET 1/1
							REV. 2